

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.  
 Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.  
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

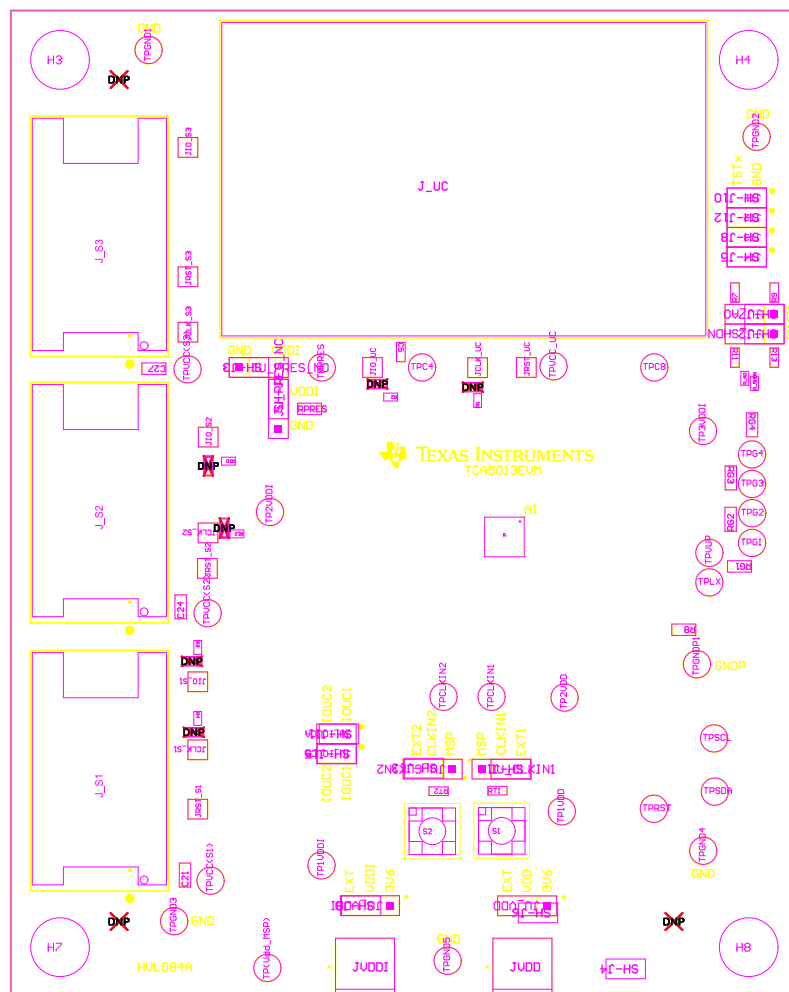
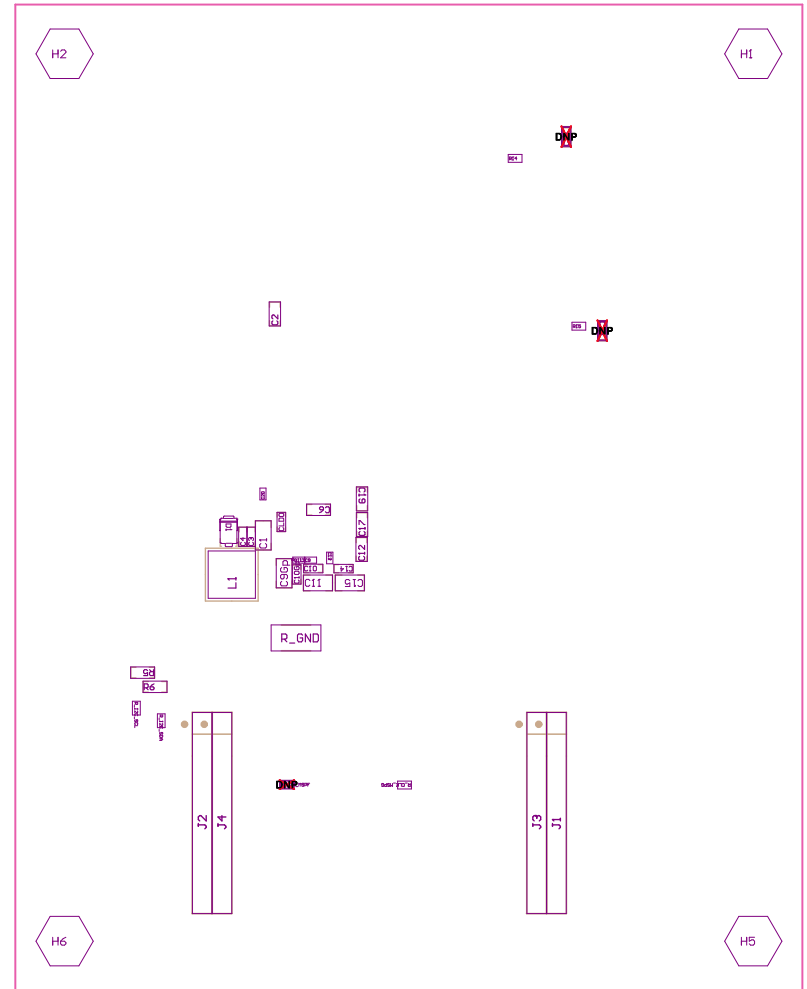


TABLE 1	
Variant	Label text
001	TCA5013EUM

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: HUL084	REV: A	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 5/16/2014 12:57:34 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: HUL084	REV: A	SUN REV: Not In VersionControl
		IGNORE -> Bottom Overlay	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/16/2014	12:57:36 PM	TEXAS INSTRUMENTS

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